

GAP PAD TGP HC 5000

Known as GAP PAD HC 5.0 November 2018

PRODUCT DESCRIPTION

Highly Conformable, Thermally Conductive, Low Modulus Material.

Silicone
Grey
Fibreglass
*0.508, 1.016, 1.524,
2.032, 2.540, 3.175
2
Thermal management,
TIM (Thermal Interface Material)
-60 to 200°C

^{*}Custom thicknesses available. Please contact your Henkel Sales Representative for more information.

FEATURES AND BENEFITS

- Thermal Conductivity: 5.0 W/m-K
- High-compliance, low compression stress
- Fibreglass reinforced for shear and tear resistance

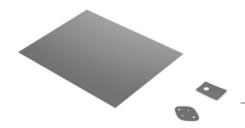
GAP PAD TGP HC 5000 is a soft and compliant gap filling material with a thermal conductivity of 5.0 W/m-K. The material offers exceptional thermal performance at low pressures due to a unique filler package and low-modulus resinformulation. The enhanced material is ideal for a pplications requiring low stress on components and boards during assembly.

GAP PAD TGP HC 5000 maintains a conformable nature that allows excellent interfacing and wet-out characteristics, even to surfaces with high roughness and/or topography.

GAP PAD TGP HC 5000 is offered with natural inherent tack on both sides of the material eliminating the need for thermally-impeding adhesive layers. The top side has minimal tack for ease of handling.

GAP PAD TGP HC 5000 is supplied with protective liners on both sides.

^{*}The product appearance was violet until 06-05-2022.



TYPICAL APPLICATIONS

- Telecommunications
- ASICs and DSPs
- Consumer electronics
- Thermal modules to heat sinks

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties		35
Hardness, Shore 00, Thirty second delay va ASTM D2240, Bulk rubber	alue,	
Heat Capacity, ASTM E1269, J/g-K		1.0
Density, Bulk rubber, ASTM D792, g/cc		3.2
Flammability, UL 94		V-0
Young's Modulus, ASTM D575 (1)	kPa (psi)	121 (17.5)

Electrical Properties

5,000
8.0
1×10 ¹⁰

Thermal Properties

5.0
0.35
0.3
0.26

(1) Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of

0.79 inch2 after 5 minutes of compression at 10% strain on a 1mm thickness material
(2) The ASTM D5470 test fixture was utilized. The recorded values include the interfacial thermal resistance. The values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied

GENERAL INFORMATION

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

Not for product specifications

The technical data contained herein are intended as reference only. Please contact HITEK Electronic Materials for assistance and recommendations on specifications for this product.

CONFIGURATIONS AVAILABLE

GAP PAD TGP HC 5000 is available in the following configurations:

Sheet form and die-cut parts



STORAGE

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: 25°C (±3), 50% RH (±10) for a 12 months shelf life. Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

 $(^{\circ}C \times 1.8) + 32 = ^{\circ}F$ kV/mm x 25.4 = V/mil mm / 25.4 = inches N x 0.225 = lb N/mm x 5.71 = lb/in psi x 145 = N/mm² MPa = N/mm² N·m x 8.851 = lb·in N·m x 0.738 = lb·ft N·mm x 0.142 = oz·in mPa·s = cP

Disclaimer

Note:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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Reference 1

